

N-channel 600 V, 0.06 Ω typ., 42 A MDmesh™ M2 Power MOSFET in a TO247-4 package

Datasheet - production data

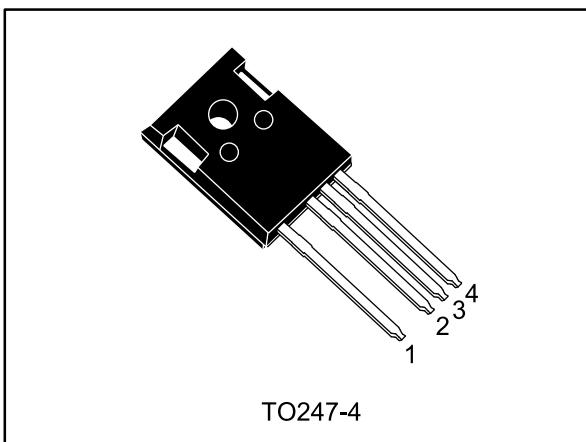
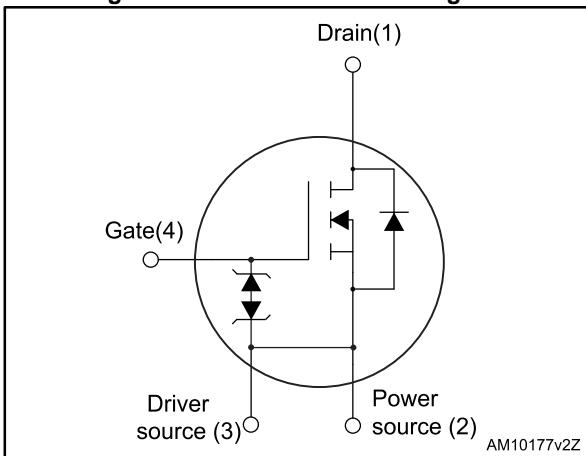


Figure 1: Internal schematic diagram



Features

Order code	V _{DS} @ T _{Jmax}	R _{D(on)} max	I _D
STW48N60M2-4	650 V	0.07 Ω	42 A

- Excellent switching performance thanks to the extra driving source pin
- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- High efficiency switching applications:
 - Servers
 - PV inverters
 - Telecom infrastructure
 - Multi kW battery chargers

Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order code	Marking	Package	Packaging
STW48N60M2-4	48N60M2	TO247-4	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate- source voltage	± 25	V
I_D	Drain current (continuous) at $T_c = 25^\circ\text{C}$	42	A
I_D	Drain current (continuous) at $T_c = 100^\circ\text{C}$	26	A
$I_{DM}^{(1)}$	Drain current (pulsed)	168	A
P_{TOT}	Total dissipation at $T_c = 25^\circ\text{C}$	300	W
I_{AR}	Max current during repetitive or single pulse avalanche (pulse width limited by T_{JMAX})	7	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	4500	mJ
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	V/ns
T_{stg}	Storage temperature	- 55 to 150	$^\circ\text{C}$
T_j	Max. operating junction temperature	150	$^\circ\text{C}$

Notes:

(1)Pulse width limited by safe operating area

(2) $I_{SD} \leq 42\text{ A}$, $di/dt = 400\text{ A}/\mu\text{s}$, $V_{DS(\text{peak})} < V_{(\text{BR})DSS}$, $V_{DD} = 400\text{ V}$ (3) $V_{DS} \leq 480\text{ V}$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	0.42	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	50	$^\circ\text{C/W}$

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 4: On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	600			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = 600 \text{ V}$			1	μA
		$V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}$			100	μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 25 \text{ V}$			± 10	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on- resistance	$V_{GS} = 10 \text{ V}, I_D = 21 \text{ A}$		0.06	0.07	Ω

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0$	-	3060	-	pF
C_{oss}	Output capacitance		-	143	-	pF
C_{rss}	Reverse transfer capacitance		-	4.3	-	pF
$C_{o(er)}^{(1)}$	Equivalent Output Capacitance	$V_{GS} = 0, V_{DS} = 0 \text{ to } 480 \text{ V}$	-	630	-	$\pi\Phi$
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz open drain}$	-	4.6	-	Ω
Q_g	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 42 \text{ A}, V_{GS} = 10 \text{ V}$	-	70	-	nC
Q_{gs}	Gate-source charge		-	10.5	-	nC
Q_{gd}	Gate-drain charge		-	31	-	nC

Notes:

⁽¹⁾ C_{oss} eq. is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 21 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	18.5	-	ns
t_r	Rise time		-	17	-	ns
$t_{d(off)}$	Turn-off-delay time		-	13	-	ns
t_f	Fall time		-	119	-	ns

Table 7: Source drain diode

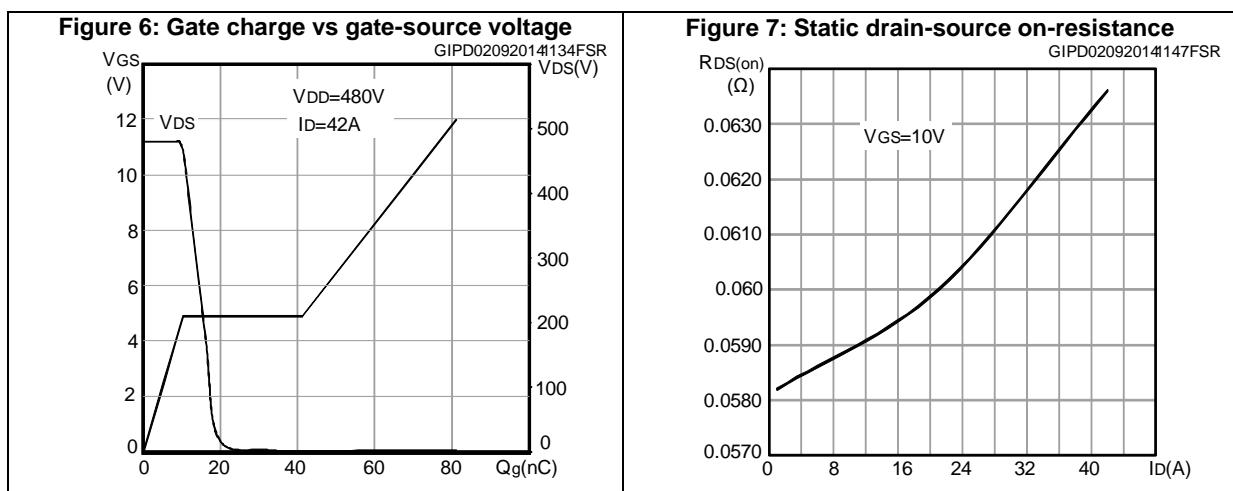
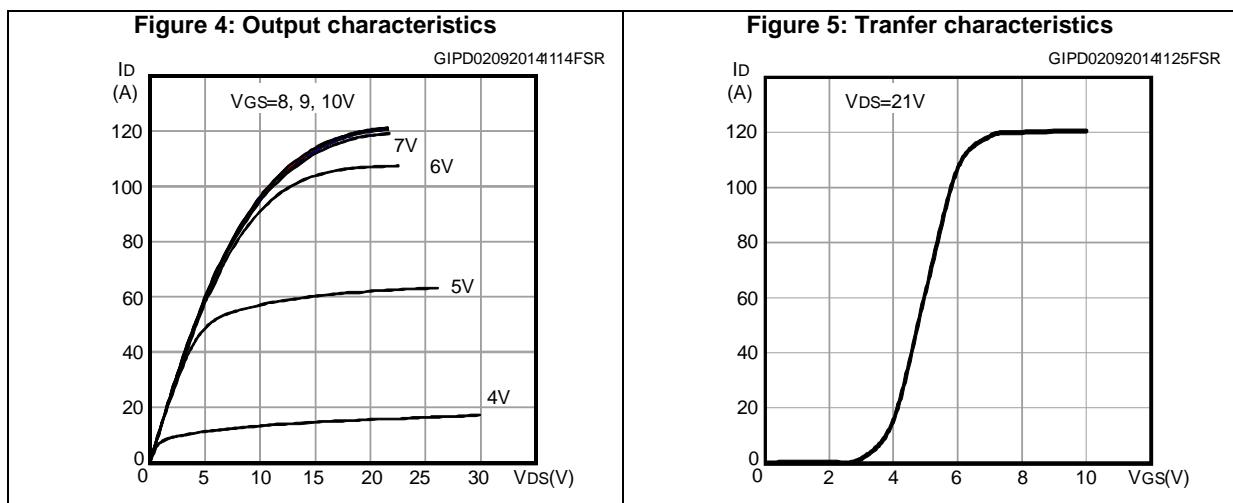
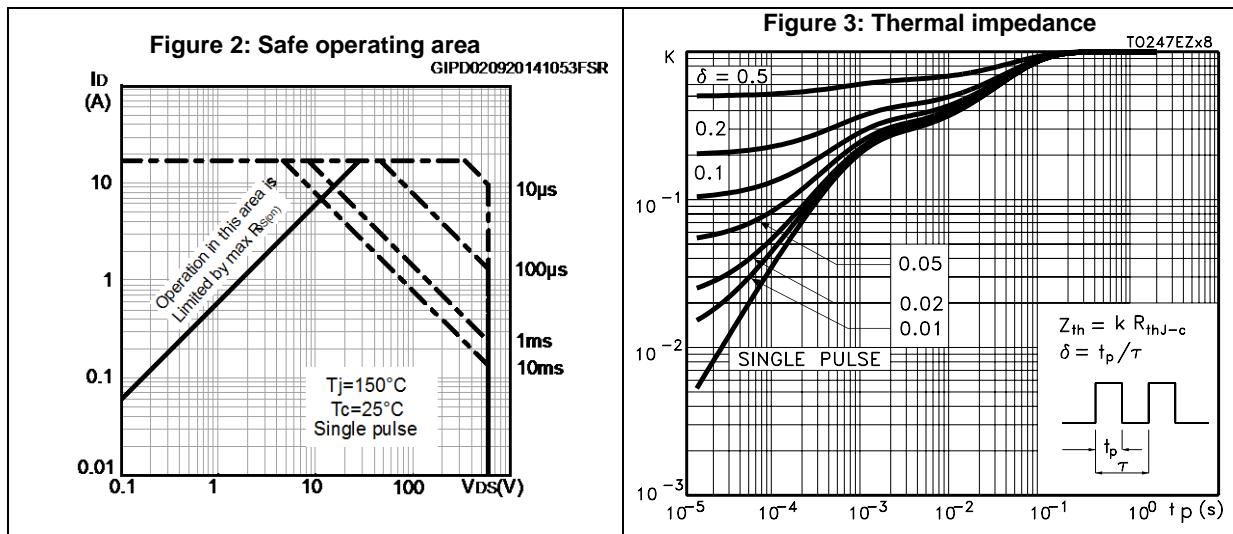
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		42	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		168	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 21 \text{ A}, V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 42 \text{ A},$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$	-	487		ns
Q_{rr}	Reverse recovery charge		-	9.1		μC
I_{RRM}	Reverse recovery current		-	37.5		A
t_{rr}	Reverse recovery time	$I_{SD} = 42 \text{ A},$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	-	605		ns
Q_{rr}	Reverse recovery charge		-	12.5		μC
I_{RRM}	Reverse recovery current		-	41.5		A

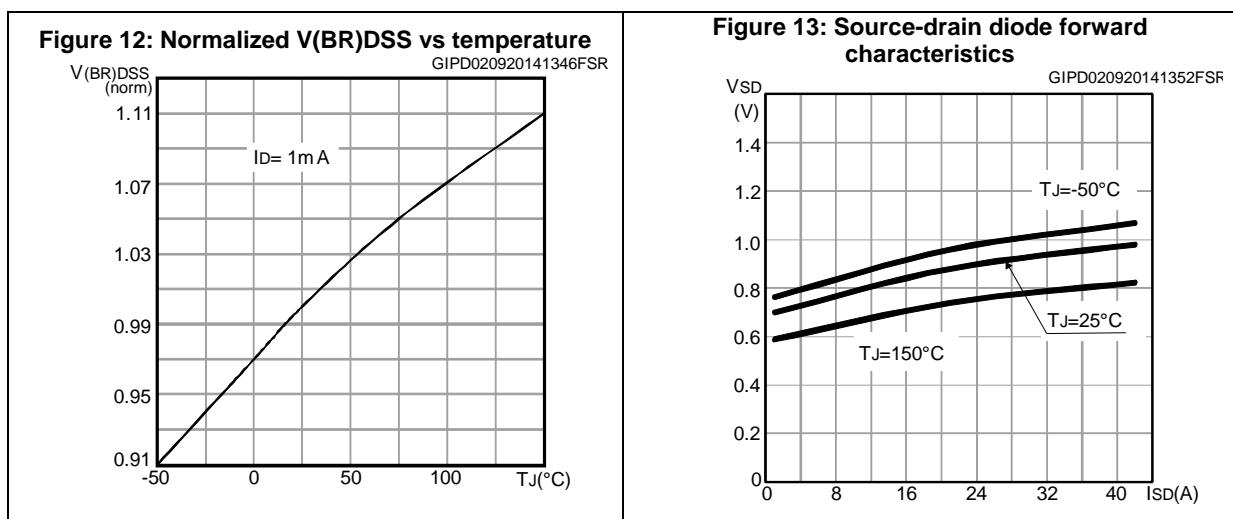
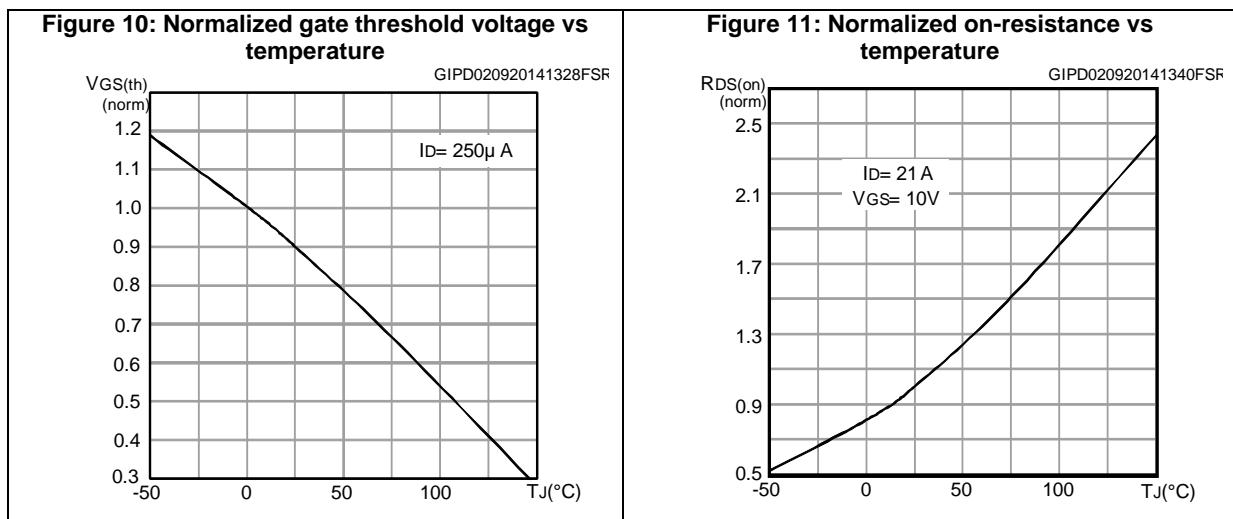
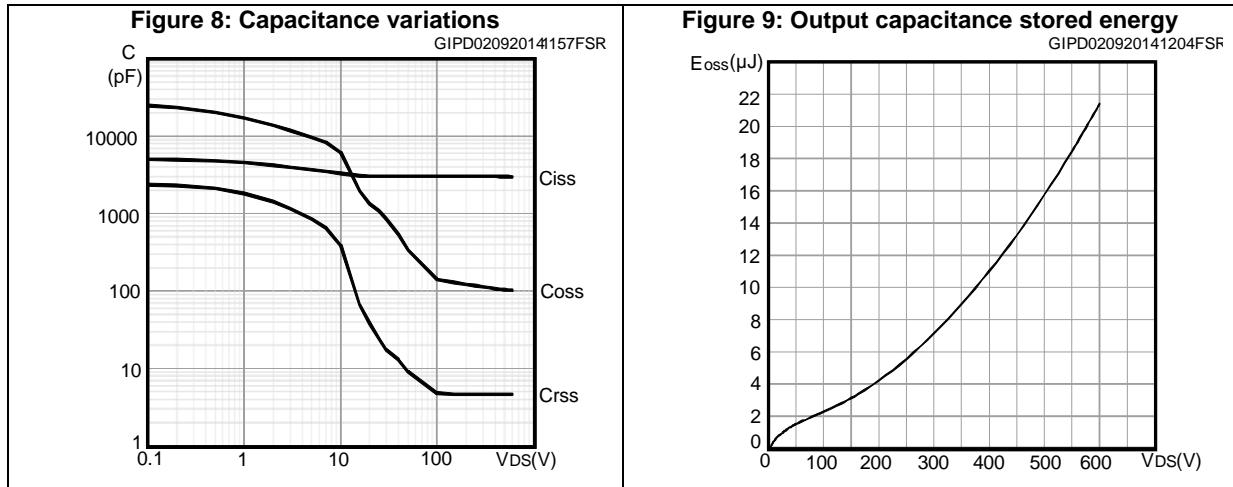
Notes:

(1)Pulse width limited by safe operating area

(2)Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.2 Electrical characteristics (curve)





3 Test circuits

Figure 14: Switching times test circuit for resistive load

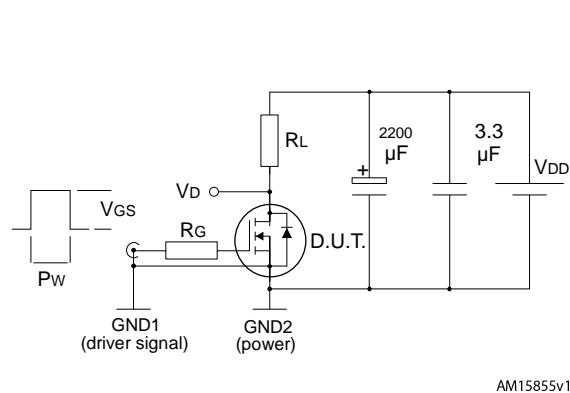


Figure 15: Gate charge test circuit

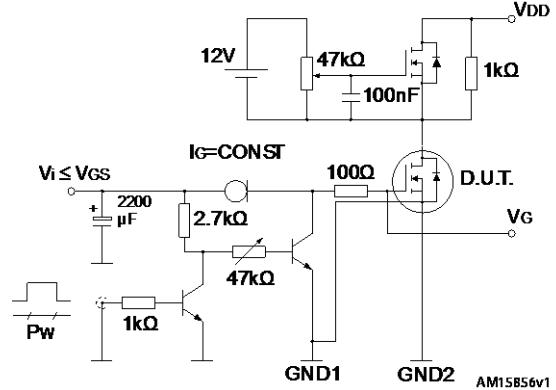


Figure 16: Test circuit for inductive load switching and diode recovery times

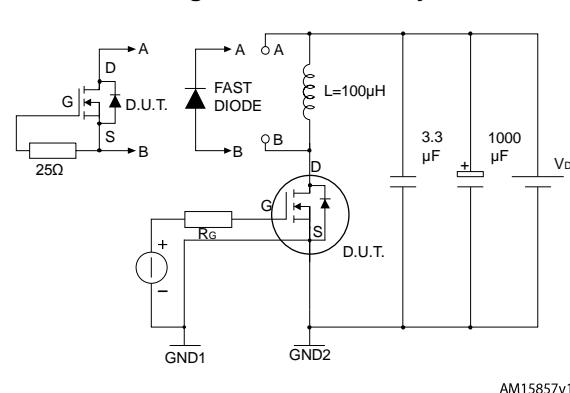


Figure 17: Unclamped inductive load test circuit

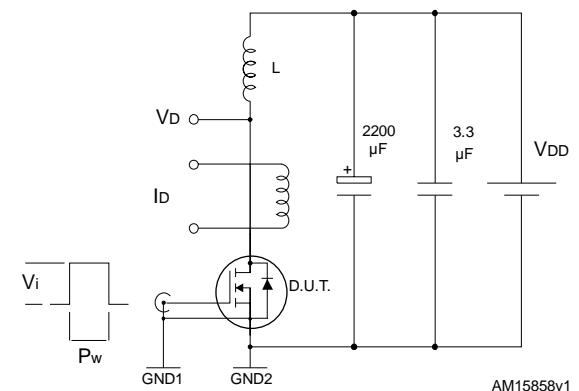


Figure 18: Unclamped inductive waveform

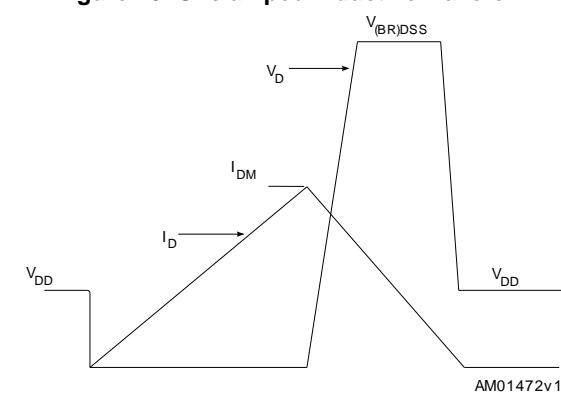
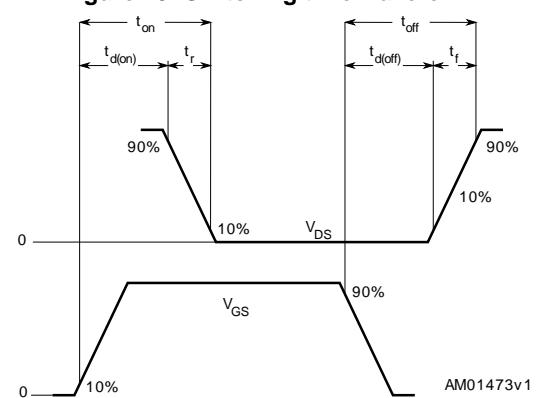


Figure 19: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
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4.1 TO247-4 package information

Figure 20: TO247-4 package outline

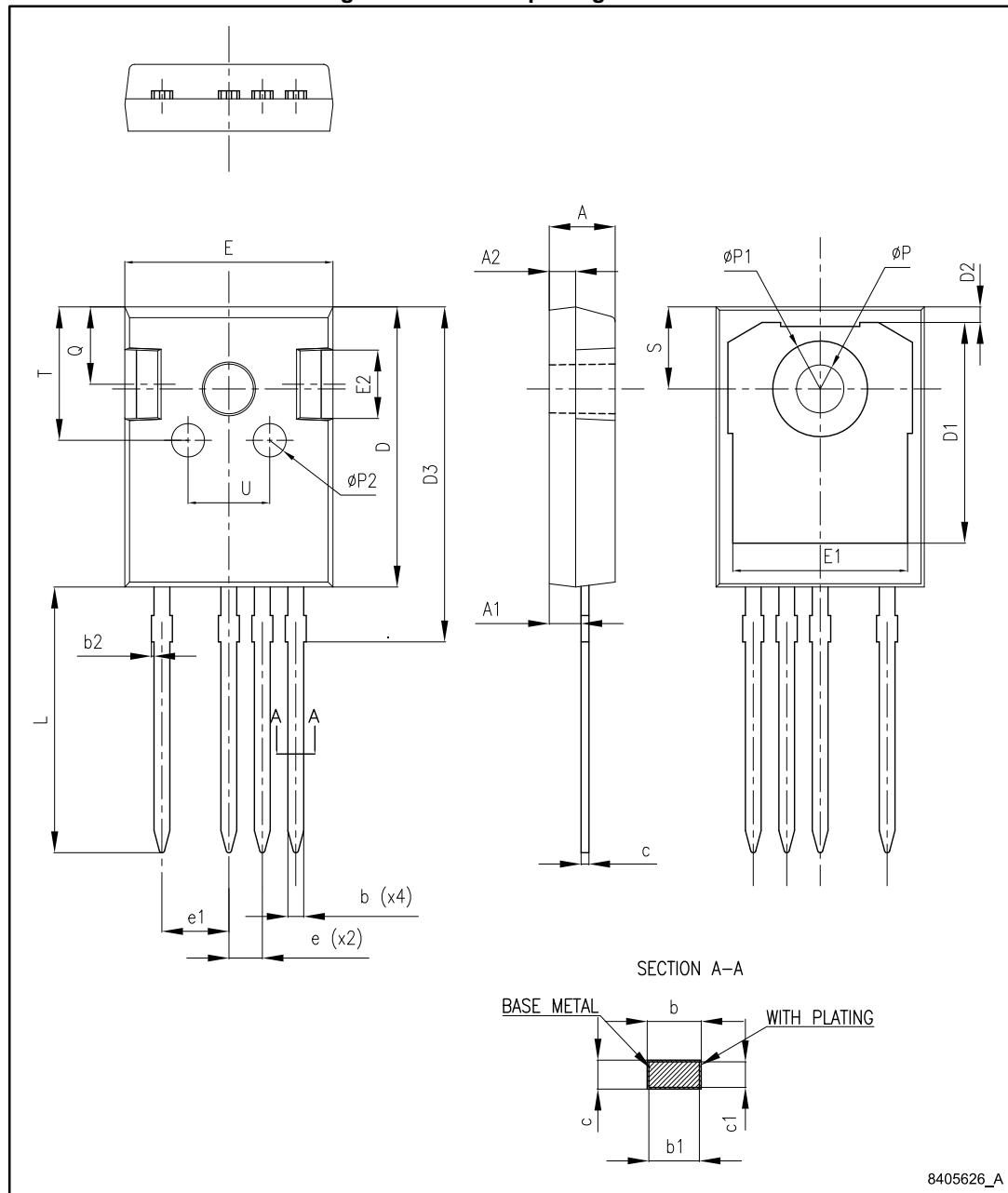


Table 8: TO247-4 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.29
b1	1.15	1.20	1.25
b2	0		0.20
c	0.59		0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
D3	24.97	25.12	25.27
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	2.44	2.54	2.64
e1	4.98	5.08	5.18
L	19.80	19.92	20.10
P	3.50	3.60	3.70
P1			7.40
P2	2.40	2.50	2.60
Q	5.60		6.00
S		6.15	
T	9.80		10.20
U	6.00		6.40

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
25-Jul-2014	1	Initial release.
30-Jan-2015	2	Added section Section 2.1: "Electrical characteristics (curve)"

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